### **DISCRETE SEMICONDUCTORS**

# DATA SHEET

**PEMB3; PUMB3** PNP/PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = open

Product specification Supersedes data of 2001 Sep 19 2003 Oct 15





### PNP/PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = open

PEMB3; PUMB3

#### **FEATURES**

- · Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- · Reduced pick and place costs.

#### **APPLICATIONS**

- · Low current peripheral drivers
- Replacement of general purpose transistors in digital applications
- · Control of IC inputs.

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	_	-50	V
Io	output current (DC)	_	-100	mA
TR1	PNP	_	_	_
TR2	PNP	_	_	_
R1	bias resistor	4.7	_	kΩ
R2	bias resistor	open	_	_

QUICK REFERENCE DATA

#### **DESCRIPTION**

PNP/PNP resistor-equipped transistors (see "Simplified outline, symbol and pinning" for package details).

#### **PRODUCT OVERVIEW**

TYPE NUMBER	PACKAGE		MARKING CODE	NPN/PNP	NPN/NPN	
TIPE NOMBER	PHILIPS	EIAJ	WARKING CODE	COMPLEMENT	COMPLEMENT	
PEMB3	SOT666	-	Z3	PEMD6	PEMH7	
PUMB3	SOT363	SC-88	B5* <sup>(1)</sup>	PUMD6	PUMH7	

#### Note

- 1. \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.
  - \* = W: Made in China.

#### SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PINNING		
ITPE NUMBER	SIMPLIFIED OUTLINE AND STIMBOL	PIN	DESCRIPTION	
PEMB3		1	emitter TR1	
PUMB3	6   5   4	2	base TR1	
		3	collector TR2	
		4	emitter TR2	
	TR1	5	base TR2	
	R1	6	collector TR1	
	1 2 3			
	Top view MAM452			

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#### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE			
TIPE NOMBER	NAME	DESCRIPTION	VERSION	
PEMB3	<ul> <li>plastic surface mounted package; 6 leads</li> </ul>		SOT666	
PUMB3	<ul> <li>plastic surface mounted package; 6 leads</li> </ul> SOT3		SOT363	

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT	
Per transistor						
$V_{CBO}$	collector-base voltage	open emitter	-	-50	V	
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-50	V	
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-5	V	
I <sub>O</sub>	output current (DC)		_	-100	mA	
I <sub>CM</sub>	peak collector current		_	-100	mA	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C				
	SOT363	note 1	_	200	mW	
	SOT666	notes 1 and 2	_	200	mW	
T <sub>stg</sub>	storage temperature		-65	+150	°C	
Tj	junction temperature		_	150	°C	
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C	
Per device	•		·	•		
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C				
	SOT363	note 1	_	300	mW	
	SOT666	notes 1 and 2	_	300	mW	

#### Notes

- 1. Device mounted on an FR4 printed-circuit board, single-sided copper, standard footprint.
- 2. Reflow soldering is the only recommended soldering method.

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#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
Per transist	tor			
R <sub>th j-a</sub>	thermal resistance from junction to ambient	T <sub>amb</sub> ≤ 25 °C		
	SOT363	note 1	625	K/W
	SOT666	notes 1 and 2	625	K/W
Per device				
R <sub>th j-a</sub>	thermal resistance from junction to ambient	T <sub>amb</sub> ≤ 25 °C		
	SOT363	note 1	416	K/W
	SOT666	note 1	416	K/W

#### **Notes**

- 1. Device mounted on an FR4 printed-circuit board, single-sided copper, standard footprint.
- 2. Reflow soldering is the only recommended soldering method.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS		TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	_	_	-100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_{B} = 0$	_	_	-1	μΑ
		$V_{CE} = -30 \text{ V}; I_B = 0; T_j = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0$	_	_	-100	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -1 \text{ mA}$	200	_	_	
V <sub>CEsat</sub>	saturation voltage	$I_C = -5 \text{ mA}; I_B = -0.25 \text{ mA}$	_	_	-100	mV
R1	input resistor		3.3	4.7	6.1	kΩ
C <sub>c</sub>	collector capacitance	$I_E = I_e = 0$ ; $V_{CB} = -10 \text{ V}$ ; $f = 1 \text{ MHz}$	_	_	3	pF

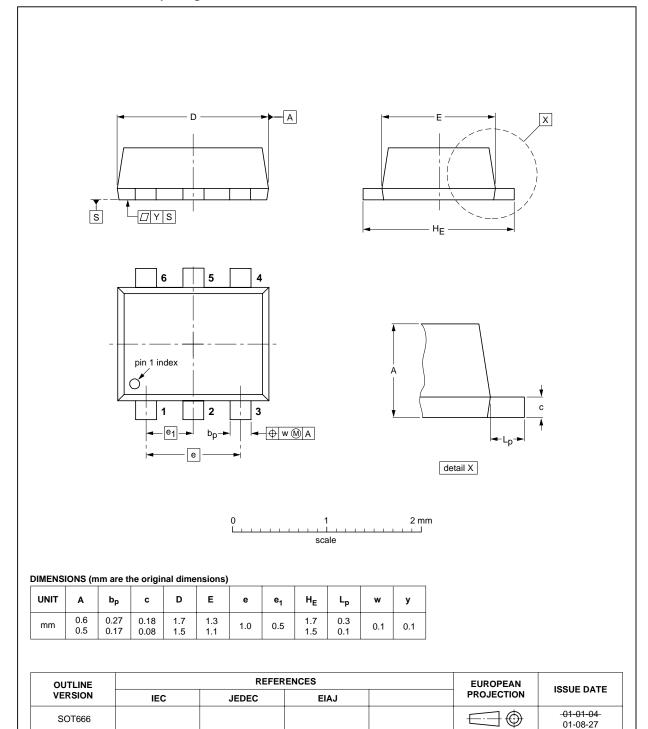
### PNP/PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = open

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#### **PACKAGE OUTLINES**

#### Plastic surface mounted package; 6 leads

**SOT666** 



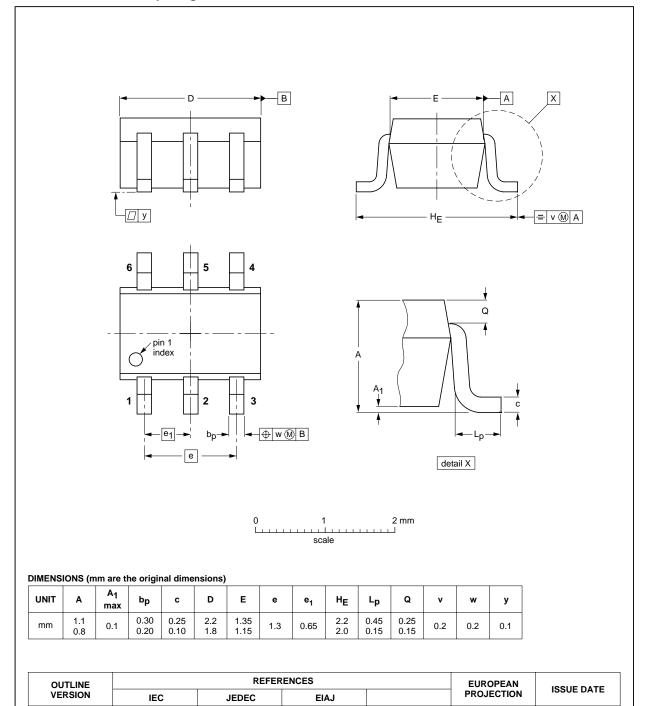
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#### Plastic surface mounted package; 6 leads

**SOT363** 



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#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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